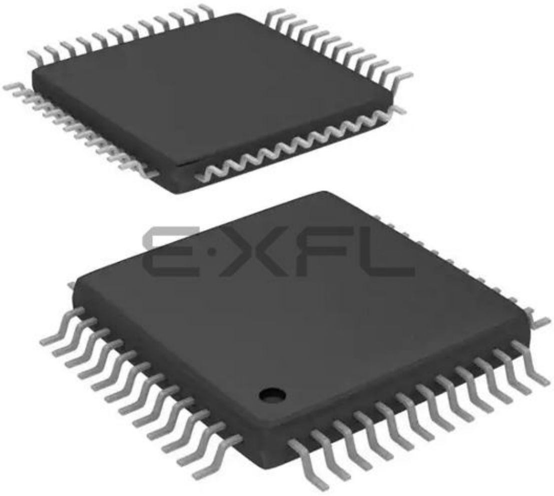

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M3
Core Size	32-Bit Single-Core
Speed	32MHz
Connectivity	I²C, IrDA, SmartCard, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	37
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	1.98V ~ 3.8V
Data Converters	A/D 4x12b; D/A 1x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	48-TQFP
Supplier Device Package	48-TQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/efm32g222f32g-e-qfp48r

Module	Module	Module
LCD	Full configuration	LCD_SEG[39:0], LCD_COM[3:0], LCD_BCAP_P, LCD_BCAP_N, LCD_BEXT

Module	Configuration	Pin Connections
LCD	Full configuration	LCD_SEG[39:0], LCD_COM[7:0], LCD_BCAP_P, LCD_BCAP_N, LCD_BEXT

4.4.5 EM4 Current Consumption

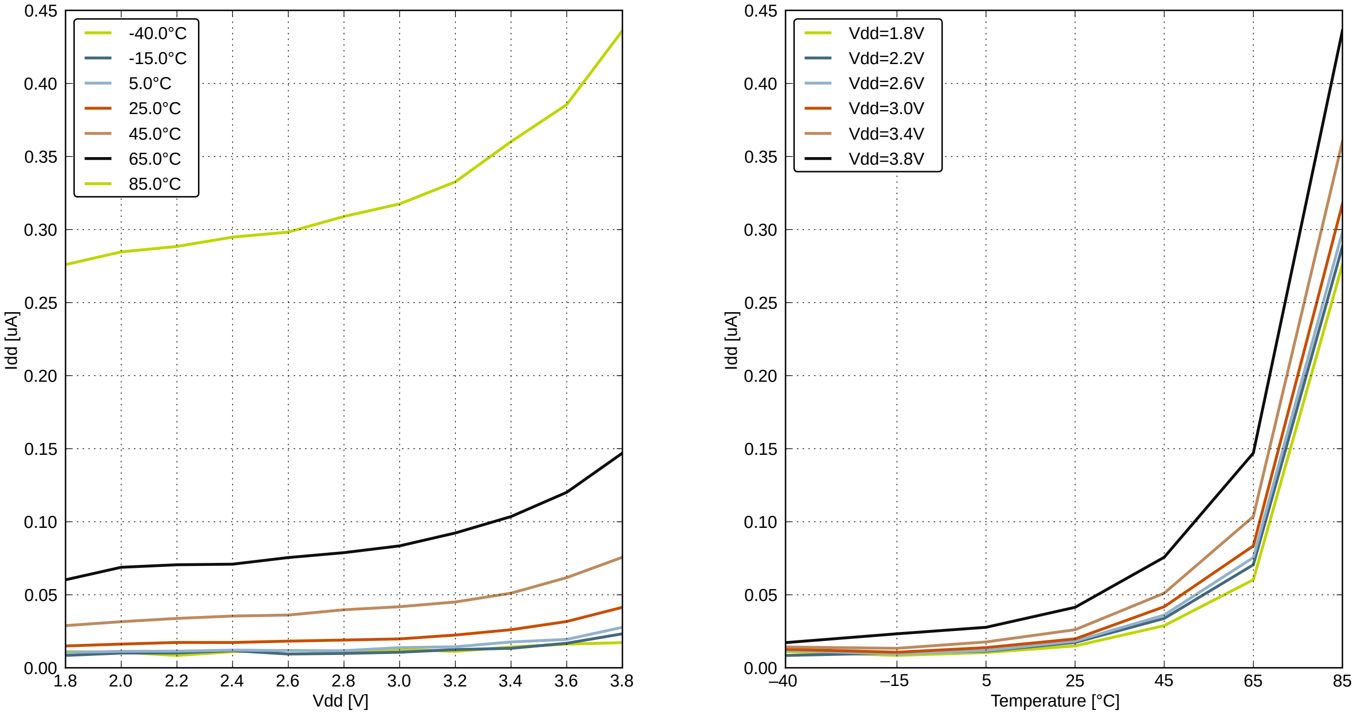

Figure 4.13. EM4 Current Consumption

4.5 Transition between Energy Modes

The transition times are measured from the trigger to the first clock edge in the CPU.

Table 4.4. Energy Modes Transitions

Parameter	Symbol	Min	Typ	Max	Unit
Transition time from EM1 to EM0	t_{EM10}	—	0	—	HFCORECLK cycles
Transition time from EM2 to EM0	t_{EM20}	—	2	—	µs
Transition time from EM3 to EM0	t_{EM30}	—	2	—	µs
Transition time from EM4 to EM0	t_{EM40}	—	163	—	µs

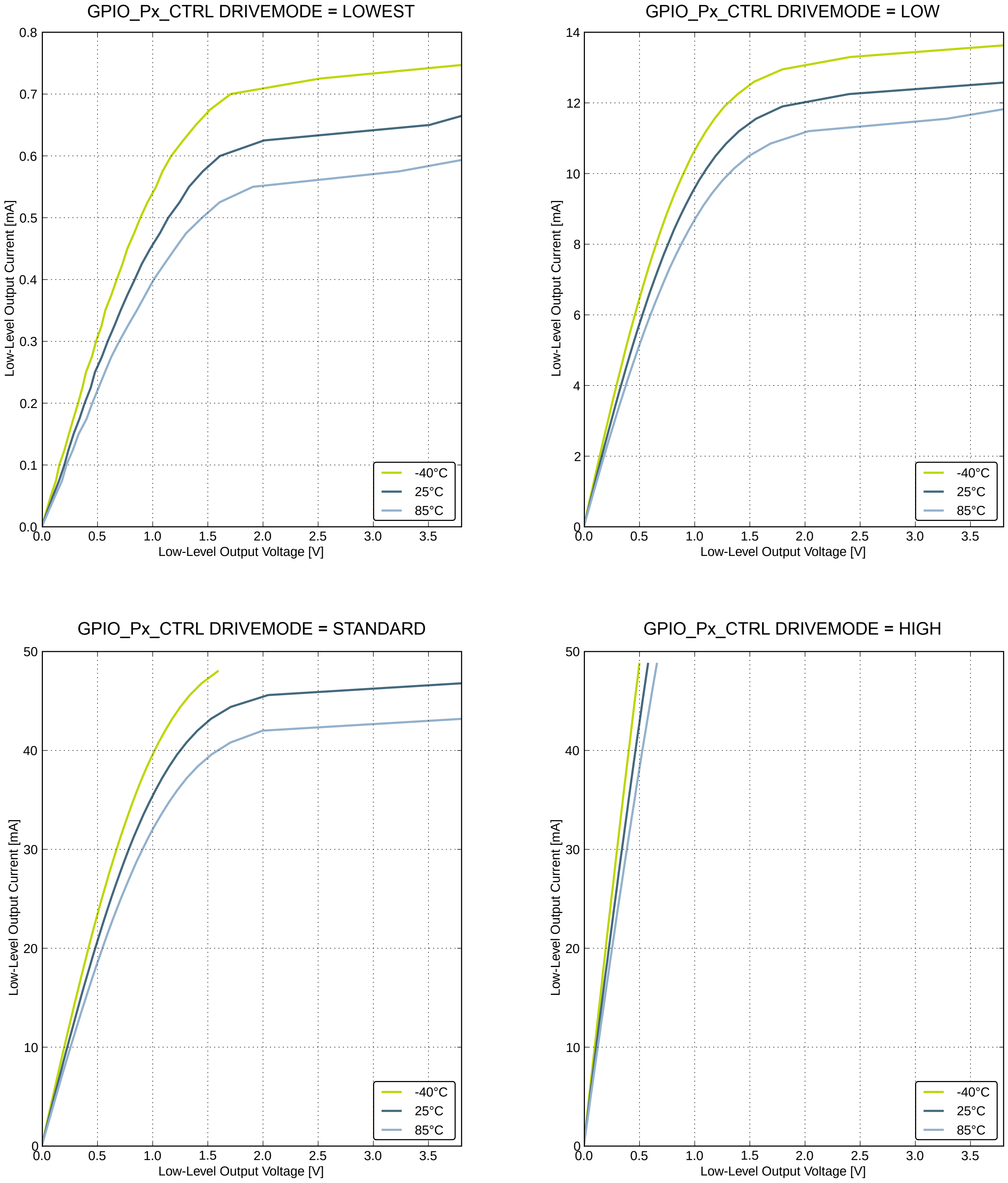

Figure 4.18. Typical Low-Level Output Current, 3.8V Supply Voltage

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Signal-to-Noise And Distortion Ratio (SINAD)	$\text{SINAD}_{\text{ADC}}$	1 MSamples/s, 12 bit, single-ended, internal 1.25 V reference, ADC_CLK = 13 MHz, BIASPROG = 0xF4B	—	58	—	dB
		1 MSamples/s, 12 bit, single-ended, internal 2.5 V reference, ADC_CLK = 13 MHz, BIASPROG = 0xF4B	—	62	—	dB
		1 MSamples/s, 12 bit, single-ended, V_{DD} reference, ADC_CLK = 13 MHz, BIASPROG = 0xF4B	—	66	—	dB
		1 MSamples/s, 12 bit, differential, internal 1.25 V reference, ADC_CLK = 13 MHz, BIASPROG = 0xF4B	—	63	—	dB
		1 MSamples/s, 12 bit, differential, internal 2.5 V reference, ADC_CLK = 13 MHz, BIASPROG = 0xF4B	—	66	—	dB
		1 MSamples/s, 12 bit, differential, 5 V reference, ADC_CLK = 13 MHz, BIASPROG = 0xF4B	—	66	—	dB
		1 MSamples/s, 12 bit, differential, V_{DD} reference, ADC_CLK = 13 MHz, BIASPROG = 0xF4B	62	68	—	dB
		1 MSamples/s, 12 bit, differential, $2xV_{DD}$ reference, ADC_CLK = 13 MHz, BIASPROG = 0xF4B	—	68	—	dB
		200 kSamples/s, 12 bit, single-ended, internal 1.25 V reference, ADC_CLK = 7 MHz, BIASPROG = 0x747	—	61	—	dB
		200 kSamples/s, 12 bit, single-ended, internal 2.5 V reference, ADC_CLK = 7 MHz, BIASPROG = 0x747	—	62	—	dB
		200 kSamples/s, 12 bit, single-ended, VDD reference, ADC_CLK = 7 MHz, BIASPROG = 0x747	—	66	—	dB
		200 kSamples/s, 12 bit, differential, internal 1.25 V reference, ADC_CLK = 7 MHz, BIASPROG = 0x747	—	63	—	dB
		200 kSamples/s, 12 bit, differential, internal 2.5 V reference, ADC_CLK = 7 MHz, BIASPROG = 0x747	—	66	—	dB
		200 kSamples/s, 12 bit, differential, 5V reference, ADC_CLK= 7 MHz, BIASPROG = 0x747	—	66	—	dB

4.13 Voltage Comparator (VCMP)

Table 4.17. VCMP

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Input voltage range	V_{VCMPIN}		—	V_{DD}	—	V
VCMP Common Mode voltage range	V_{VCMPCM}		—	V_{DD}	—	V
Active current	I_{VCMP}	BIASPROG=0b0000 and HALFBIAS=1 in VCMPn_CTRL register	—	0.3	1	µA
		BIASPROG=0b1111 and HALFBIAS=0 in VCMPn_CTRL register. LPREF=0.	—	22	30	µA
Startup time reference generator	$t_{VCMPREF}$	NORMAL	—	10	—	µs
Offset voltage	$V_{VCMPOFFSET}$	Single-ended	—	10	—	mV
		Differential	—	10	—	mV
VCMP hysteresis	$V_{VCMPHYST}$		—	40	—	mV
Startup time	$t_{VCMPSTART}$		—	—	10	µs

The $V_{DD\ Trigger\ Level}$ can be configured by setting the TRIGLEVEL field of the VCMP_CTRL register in accordance with the following equation:

$$V_{DD\ Trigger\ Level} = 1.667V + 0.034 \times \mathrm{TRIGLEVEL}$$

Table 4.21. I2C Fast-mode Plus (Fm+)

Parameter	Symbol	Min	Typ	Max	Unit
SCL clock frequency	f_{SCL}	0	—	1000[1]	kHz
SCL clock low time	t_{LOW}	0.5	—	—	µs
SCL clock high time	t_{HIGH}	0.26	—	—	µs
SDA set-up time	$t_{SU,DAT}$	50	—	—	ns
SDA hold time	$t_{HD,DAT}$	8	—	—	ns
Repeated START condition set-up time	$t_{SU,STA}$	0.26	—	—	µs
(Repeated) START condition hold time	$t_{HD,STA}$	0.26	—	—	µs
STOP condition set-up time	$t_{SU,STO}$	0.26	—	—	µs
Bus free time between a STOP and a START condition	t_{BUF}	0.5	—	—	µs

Note:

1. For the minimum HFPERCLK frequency required in Fast-mode Plus, see the I2C chapter in the EFM32G Reference Manual.

4.16 Digital Peripherals

Table 4.22. Digital Peripherals

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
USART current	I_{USART}	USART idle current, clock enabled	—	7.5	—	µA/MHz
UART current	I_{UART}	UART idle current, clock enabled	—	5.63	—	µA/MHz
LEUART current	I_{LEUART}	LEUART idle current, clock enabled	—	150	—	nA
I2C current	I_{I2C}	I2C idle current, clock enabled	—	6.25	—	µA/MHz
TIMER current	I_{TIMER}	TIMER_0 idle current, clock enabled	—	8.75	—	µA/MHz
LETIMER current	$I_{LETIMER}$	LETIMER idle current, clock enabled	—	150	—	nA
PCNT current	I_{PCNT}	PCNT idle current, clock enabled	—	100	—	nA
RTC current	I_{RTC}	RTC idle current, clock enabled	—	100	—	nA
LCD current	I_{LCD}	LCD idle current, clock enabled	—	100	—	nA
AES current	I_{AES}	AES idle current, clock enabled	—	2.5	—	µA/MHz
GPIO current	I_{GPIO}	GPIO idle current, clock enabled	—	5.31	—	µA/MHz
EBI current	I_{EBI}	EBI idle current, clock enabled	—	1.56	—	µA/MHz
PRS current	I_{PRS}	PRS idle current	—	2.81	—	µA/MHz
DMA current	I_{DMA}	Clock enable	—	8.12	—	µA/MHz

Note: Please refer to the application note "AN0002 EFM32 Hardware Design Considerations" forguidelines on designing Printed Circuit Boards (PCB's) for the EFM32G.

Alternate	LOCATION				
Functionality	0	1	2	3	Description
LETIM0_OUT1	PD7		PF1		Low Energy Timer LETIM0, output channel 1.
LEU0_RX	PD5	PB14			LEUART0 Receive input.
LEU0_TX	PD4	PB13			LEUART0 Transmit output. Also used as receive input in half duplex communication.
LFXTAL_N	PB8				Low Frequency Crystal (typically 32.768 kHz) negative pin. Also used as an optional external clock input pin.
LFXTAL_P	PB7				Low Frequency Crystal (typically 32.768 kHz) positive pin.
PCNT0_S0IN	PC13		PC0		Pulse Counter PCNT0 input number 0.
PCNT0_S1IN	PC14		PC1		Pulse Counter PCNT0 input number 1.
TIM0_CC0	PA0	PA0			Timer 0 Capture Compare input / output channel 0.
TIM0_CC1	PA1	PA1			Timer 0 Capture Compare input / output channel 1.
TIM0_CC2	PA2	PA2			Timer 0 Capture Compare input / output channel 2.
TIM0_CDTI0		PC13		PC13	Timer 0 Complimentary Deat Time Insertion channel 0.
TIM0_CDTI1		PC14		PC14	Timer 0 Complimentary Deat Time Insertion channel 1.
TIM0_CDTI2		PC15		PC15	Timer 0 Complimentary Deat Time Insertion channel 2.
TIM1_CC0	PC13	PE10			Timer 1 Capture Compare input / output channel 0.
TIM1_CC1	PC14	PE11			Timer 1 Capture Compare input / output channel 1.
TIM1_CC2	PC15	PE12			Timer 1 Capture Compare input / output channel 2.
US0_CLK	PE12				USART0 clock input / output.
US0_CS	PE13				USART0 chip select input / output.
US0_RX	PE11				USART0 Asynchronous Receive. USART0 Synchronous mode Master Input / Slave Output (MISO).
US0_TX	PE10				USART0 Asynchronous Transmit.Also used as receive input in half duplex communication. USART0 Synchronous mode Master Output / Slave Input (MOSI).
US1_CLK	PB7				USART1 clock input / output.
US1_CS	PB8				USART1 chip select input / output.
US1_RX	PC1				USART1 Asynchronous Receive. USART1 Synchronous mode Master Input / Slave Output (MISO).
US1_TX	PC0				USART1 Asynchronous Transmit.Also used as receive input in half duplex communication. USART1 Synchronous mode Master Output / Slave Input (MOSI).

TQFP64 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	**Pin Name**	**Analog**	**Timers**	**Communication**	**Other**
6	PA5		TIM0_CDTI2 #0	LEU1_TX #1	
7	IOVDD_0	Digital IO power supply 0.			
8	VSS	Ground.			
9	PC0	ACMP0_CH0	PCNT0_S0IN #1	US1_TX #1	
10	PC1	ACMP0_CH1	PCNT0_S1IN #1	US1_RX #1	
11	PC2	ACMP0_CH2		US1_CLK #1	
12	PC3	ACMP0_CH3		US1_CS #1	
13	PC4	ACMP0_CH4	LETIM0_OUT0 #3 PCNT1_S0IN #0	US2_CLK #0	
14	PC5	ACMP0_CH5	LETIM0_OUT1 #3 PCNT1_S1IN #0	US2_CS #0	
15	PB7	LFXTAL_P		US1_CLK #0	
16	PB8	LFXTAL_N		US1_CS #0	
17	PA8		TIM2_CC0 #0		
18	PA9		TIM2_CC1 #0		
19	PA10		TIM2_CC2 #0		
20	RESETn	Reset input, active low.To apply an external reset source to this pin, it is required to only drive this pin low during reset, and let the internal pull-up ensure that reset is released.			
21	PB11	DAC0_OUT0	LETIM0_OUT0 #1		
22	VSS	Ground.			
23	AVDD_1	Analog power supply 1.			
24	PB13	HFXTAL_P		LEU0_TX #1	
25	PB14	HFXTAL_N		LEU0_RX #1	
26	IOVDD_3	Digital IO power supply 3.			
27	AVDD_0	Analog power supply 0.			
28	PD0	ADC0_CH0	PCNT2_S0IN #0	US1_TX #1	
29	PD1	ADC0_CH1	TIM0_CC0 #3 PCNT2_S1IN #0	US1_RX #1	
30	PD2	ADC0_CH2	TIM0_CC1 #3	US1_CLK #1	
31	PD3	ADC0_CH3	TIM0_CC2 #3	US1_CS #1	
32	PD4	ADC0_CH4		LEU0_TX #0	
33	PD5	ADC0_CH5		LEU0_RX #0	
34	PD6	ADC0_CH6	LETIM0_OUT0 #0	I2C0_SDA #1	
35	PD7	ADC0_CH7	LETIM0_OUT1 #0	I2C0_SCL #1	
36	PD8				CMU_CLK1 #1
37	PC6	ACMP0_CH6		LEU1_TX #0 I2C0_SDA #2	
38	PC7	ACMP0_CH7		LEU1_RX #0 I2C0_SCL #2	

TQFP64 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	**Pin Name**	**Analog**	**Timers**	**Communication**	**Other**
39	VDD_DREG	Power supply for on-chip voltage regulator.			
40	DECOUPLE	Decouple output for on-chip voltage regulator. An external capacitance of size $C_{DECOUPLE}$ is required at this pin.			
41	PC8	ACMP1_CH0	TIM2_CC0 #2	US0_CS #2	
42	PC9	ACMP1_CH1	TIM2_CC1 #2	US0_CLK #2	
43	PC10	ACMP1_CH2	TIM2_CC2 #2	US0_RX #2	
44	PC11	ACMP1_CH3		US0_TX #2	
45	PC12	ACMP1_CH4			CMU_CLK0 #1
46	PC13	ACMP1_CH5	TIM0_CDTI0 #1/3 TIM1_CC0 #0 PCNT0_S0IN #0		
47	PC14	ACMP1_CH6	TIM0_CDTI1 #1/3 TIM1_CC1 #0 PCNT0_S1IN #0		
48	PC15	ACMP1_CH7	TIM0_CDTI2 #1/3 TIM1_CC2 #0		DBG_SWO #1
49	PF0		LETIM0_OUT0 #2		DBG_SWCLK #0/1
50	PF1		LETIM0_OUT1 #2		DBG_SWDIO #0/1
51	PF2				ACMP1_O #0 DBG_SWO #0
52	PF3		TIM0_CDTI0 #2		
53	PF4		TIM0_CDTI1 #2		
54	PF5		TIM0_CDTI2 #2		
55	IOVDD_5	Digital IO power supply 5.			
56	VSS	Ground.			
57	PE8		PCNT2_S0IN #1		
58	PE9		PCNT2_S1IN #1		
59	PE10		TIM1_CC0 #1	US0_TX #0	BOOT_TX
60	PE11		TIM1_CC1 #1	US0_RX #0	BOOT_RX
61	PE12		TIM1_CC2 #1	US0_CLK #0	
62	PE13			US0_CS #0	ACMP0_O #0
63	PE14			LEU0_TX #2	
64	PE15			LEU0_RX #2	

BGA112 Pin# and Name		Pin Alternate Functionality / Description				
Pin #	Pin Name	Analog	EBI	Timers	Communication	Other
D3	PB15					
D4	VSS	Ground.				
D5	IOVDD_6	Digital IO power supply 6.				
D6	PD9	LCD_SEG28	EBI_CS0 #0			
D7	IOVDD_5	Digital IO power supply 5.				
D8	PF1			LETIM0_OUT1 #2		DBG_SWDIO #0/1
D9	PE7				US0_TX #1	
D10	PC8	ACMP1_CH0		TIM2_CC0 #2	US0_CS #2	
D11	PC9	ACMP1_CH1		TIM2_CC1 #2	US0_CLK #2	
E1	PA6		EBI_AD15 #0		LEU1_RX #1	
E2	PA5		EBI_AD14 #0	TIM0_CDTI2 #0	LEU1_TX #1	
E3	PA4		EBI_AD13 #0	TIM0_CDTI1 #0	U0_RX #2	
E4	PB0			TIM1_CC0 #2		
E8	PF0			LETIM0_OUT0 #2		DBG_SWCLK #0/1
E9	PE0			PCNT0_S0IN #1	U0_TX #1	
E10	PE1			PCNT0_S1IN #1	U0_RX #1	
E11	PE3					ACMP1_O #1
F1	PB1			TIM1_CC1 #2		
F2	PB2			TIM1_CC2 #2		
F3	PB3			PCNT1_S0IN #1	US2_TX #1	
F4	PB4			PCNT1_S1IN #1	US2_RX #1	
F8	VDD_DREG	Power supply for on-chip voltage regulator.				
F9	VSS_DREG	Ground for on-chip voltage regulator.				
F10	PE2					ACMP0_O #1
F11	DECOUPLE	Decouple output for on-chip voltage regulator. An external capacitance of size $C_{DECOUPLE}$ is required at this pin.				
G1	PB5				US2_CLK #1	
G2	PB6				US2_CS #1	
G3	VSS	Ground.				
G4	IOVDD_0	Digital IO power supply 0.				
G8	IOVDD_4	Digital IO power supply 4.				
G9	VSS	Ground.				

BGA112 Pin# and Name		Pin Alternate Functionality / Description				
Pin #	**Pin Name**	**Analog**	**EBI**	**Timers**	**Communication**	**Other**
K5	PA11					
K6	RESETn	Reset input, active low.To apply an external reset source to this pin, it is required to only drive this pin low during reset, and let the internal pull-up ensure that reset is released.				
K7	AVSS_1	Analog ground 1.				
K8	AVDD_2	Analog power supply 2.				
K9	AVDD_1	Analog power supply 1.				
K10	AVSS_0	Analog ground 0.				
K11	PD1	ADC0_CH1		TIM0_CC0 #3 PCNT2_S1IN #0	US1_RX #1	
L1	PB8	LFXTAL_N			US1_CS #0	
L2	PC5	ACMP0_CH5		LETIM0_OUT1 #3 PCNT1_S1IN #0	US2_CS #0	
L3	PA14			TIM2_CC2 #1		
L4	IOVDD_1	Digital IO power supply 1.				
L5	PB11	DAC0_OUT0		LETIM0_OUT0 #1		
L6	PB12	DAC0_OUT1		LETIM0_OUT1 #1		
L7	AVSS_2	Analog ground 2.				
L8	PB13	HFXTAL_P			LEU0_TX #1	
L9	PB14	HFXTAL_N			LEU0_RX #1	
L10	AVDD_0	Analog power supply 0.				
L11	PD0	ADC0_CH0		PCNT2_S0IN #0	US1_TX #1	

Alternate	LOCATION				
Functionality	0	1	2	3	Description
EBI_ARDY	PF2				External Bus Interface (EBI) Hardware Ready Control input.
EBI_CS0	PD9				External Bus Interface (EBI) Chip Select output 0.
EBI_CS1	PD10				External Bus Interface (EBI) Chip Select output 1.
EBI_CS2	PD11				External Bus Interface (EBI) Chip Select output 2.
EBI_CS3	PD12				External Bus Interface (EBI) Chip Select output 3.
EBI_REn	PF5				External Bus Interface (EBI) Read Enable output.
EBI_WEn	PF4				External Bus Interface (EBI) Write Enable output.
HFXTAL_N	PB14				High Frequency Crystal negative pin. Also used as external optional clock input pin.
HFXTAL_P	PB13				High Frequency Crystal positive pin.
I2C0_SCL	PA1	PD7	PC7	PD15	I2C0 Serial Clock Line input / output.
I2C0_SDA	PA0	PD6	PC6	PD14	I2C0 Serial Data input / output.
LETIM0_OUT0	PD6	PB11	PF0	PC4	Low Energy Timer LETIM0, output channel 0.
LETIM0_OUT1	PD7	PB12	PF1	PC5	Low Energy Timer LETIM0, output channel 1.
LEU0_RX	PD5	PB14	PE15		LEUART0 Receive input.
LEU0_TX	PD4	PB13	PE14		LEUART0 Transmit output. Also used as receive input in half duplex communication.
LEU1_RX	PC7	PA6			LEUART1 Receive input.
LEU1_TX	PC6	PA5			LEUART1 Transmit output. Also used as receive input in half duplex communication.
LFXTAL_N	PB8				Low Frequency Crystal (typically 32.768 kHz) negative pin. Also used as an optional external clock input pin.
LFXTAL_P	PB7				Low Frequency Crystal (typically 32.768 kHz) positive pin.
PCNT0_S0IN	PC13	PE0	PC0		Pulse Counter PCNT0 input number 0.
PCNT0_S1IN	PC14	PE1	PC1		Pulse Counter PCNT0 input number 1.
PCNT1_S0IN	PC4	PB3			Pulse Counter PCNT1 input number 0.
PCNT1_S1IN	PC5	PB4			Pulse Counter PCNT1 input number 1.
PCNT2_S0IN	PD0	PE8			Pulse Counter PCNT2 input number 0.
PCNT2_S1IN	PD1	PE9			Pulse Counter PCNT2 input number 1.
TIM0_CC0	PA0	PA0	PF6	PD1	Timer 0 Capture Compare input / output channel 0.
TIM0_CC1	PA1	PA1	PF7	PD2	Timer 0 Capture Compare input / output channel 1.
TIM0_CC2	PA2	PA2	PF8	PD3	Timer 0 Capture Compare input / output channel 2.
TIM0_CDTI0	PA3	PC13	PF3	PC13	Timer 0 Complimentary Deat Time Insertion channel 0.
TIM0_CDTI1	PA4	PC14	PF4	PC14	Timer 0 Complimentary Deat Time Insertion channel 1.
TIM0_CDTI2	PA5	PC15	PF5	PC15	Timer 0 Complimentary Deat Time Insertion channel 2.
TIM1_CC0	PC13	PE10	PB0		Timer 1 Capture Compare input / output channel 0.
TIM1_CC1	PC14	PE11	PB1		Timer 1 Capture Compare input / output channel 1.
TIM1_CC2	PC15	PE12	PB2		Timer 1 Capture Compare input / output channel 2.

5.8.2 Alternate Functionality Pinout

A wide selection of alternate functionality is available for multiplexing to various pins. This is shown in the following table. The table shows the name of the alternate functionality in the first column, followed by columns showing the possible LOCATION bitfield settings.

Note: Some functionality, such as analog interfaces, do not have alternate settings or a LOCATION bitfield. In these cases, the pinout is shown in the column corresponding to LOCATION 0.

Table 5.23. Alternate functionality overview

Alternate	LOCATION				
Functionality	0	1	2	3	Description
ACMP0_CH4	PC4				Analog comparator ACMP0, channel 4.
ACMP0_CH5	PC5				Analog comparator ACMP0, channel 5.
ACMP0_CH6	PC6				Analog comparator ACMP0, channel 6.
ACMP0_CH7	PC7				Analog comparator ACMP0, channel 7.
ACMP0_O	PE13				Analog comparator ACMP0, digital output.
ACMP1_CH4	PC12				Analog comparator ACMP1, channel 4.
ACMP1_CH5	PC13				Analog comparator ACMP1, channel 5.
ACMP1_CH6	PC14				Analog comparator ACMP1, channel 6.
ACMP1_CH7	PC15				Analog comparator ACMP1, channel 7.
ACMP1_O	PF2				Analog comparator ACMP1, digital output.
ADC0_CH0	PD0				Analog to digital converter ADC0, input channel number 0.
ADC0_CH1	PD1				Analog to digital converter ADC0, input channel number 1.
ADC0_CH2	PD2				Analog to digital converter ADC0, input channel number 2.
ADC0_CH3	PD3				Analog to digital converter ADC0, input channel number 3.
ADC0_CH4	PD4				Analog to digital converter ADC0, input channel number 4.
ADC0_CH5	PD5				Analog to digital converter ADC0, input channel number 5.
ADC0_CH6	PD6				Analog to digital converter ADC0, input channel number 6.
ADC0_CH7	PD7				Analog to digital converter ADC0, input channel number 7.
BOOT_RX	PE11				Bootloader RX.
BOOT_TX	PE10				Bootloader TX.
CMU_CLK0	PA2	PC12			Clock Management Unit, clock output number 0.
CMU_CLK1	PA1	PD8			Clock Management Unit, clock output number 1.
DAC0_OUT0	PB11				Digital to Analog Converter DAC0 output channel number 0.
DBG_SWCLK	PF0	PF0			Debug-interface Serial Wire clock input. Note that this function is enabled to pin out of reset, and has a built-in pull down.
DBG_SWDIO	PF1	PF1			Debug-interface Serial Wire data input / output. Note that this function is enabled to pin out of reset, and has a built-in pull up.

Alternate	LOCATION				
Functionality	0	1	2	3	Description
TIM0_CDTI1	PA4	PC14	PF4	PC14	Timer 0 Complimentary Deat Time Insertion channel 1.
TIM0_CDTI2	PA5	PC15	PF5	PC15	Timer 0 Complimentary Deat Time Insertion channel 2.
TIM1_CC0	PC13	PE10	PB0		Timer 1 Capture Compare input / output channel 0.
TIM1_CC1	PC14	PE11	PB1		Timer 1 Capture Compare input / output channel 1.
TIM1_CC2	PC15	PE12	PB2		Timer 1 Capture Compare input / output channel 2.
TIM2_CC0	PA8	PA12	PC8		Timer 2 Capture Compare input / output channel 0.
TIM2_CC1	PA9	PA13	PC9		Timer 2 Capture Compare input / output channel 1.
TIM2_CC2	PA10	PA14	PC10		Timer 2 Capture Compare input / output channel 2.
U0_RX	PF7	PE1	PA4	PC15	UART0 Receive input.
U0_TX	PF6	PE0	PA3	PC14	UART0 Transmit output. Also used as receive input in half duplex communication.
US0_CLK	PE12	PE5	PC9		USART0 clock input / output.
US0_CS	PE13	PE4	PC8		USART0 chip select input / output.
US0_RX	PE11	PE6	PC10		USART0 Asynchronous Receive. USART0 Synchronous mode Master Input / Slave Output (MISO).
US0_TX	PE10	PE7	PC11		USART0 Asynchronous Transmit.Also used as receive input in half duplex communication. USART0 Synchronous mode Master Output / Slave Input (MOSI).
US1_CLK	PB7	PD2			USART1 clock input / output.
US1_CS	PB8	PD3			USART1 chip select input / output.
US1_RX	PC1	PD1			USART1 Asynchronous Receive. USART1 Synchronous mode Master Input / Slave Output (MISO).
US1_TX	PC0	PD0			USART1 Asynchronous Transmit.Also used as receive input in half duplex communication. USART1 Synchronous mode Master Output / Slave Input (MOSI).
US2_CLK	PC4	PB5			USART2 clock input / output.
US2_CS	PC5	PB6			USART2 chip select input / output.
US2_RX	PC3	PB4			USART2 Asynchronous Receive. USART2 Synchronous mode Master Input / Slave Output (MISO).
US2_TX	PC2	PB3			USART2 Asynchronous Transmit.Also used as receive input in half duplex communication. USART2 Synchronous mode Master Output / Slave Input (MOSI).

Alternate	LOCATION				
Functionality	0	1	2	3	Description
LCD_SEG30	PD11				LCD segment line 30. Segments 28, 29, 30 and 31 are controlled by SEGEN7.
LCD_SEG31	PD12				LCD segment line 31. Segments 28, 29, 30 and 31 are controlled by SEGEN7.
LCD_SEG32	PB0				LCD segment line 32. Segments 32, 33, 34 and 35 are controlled by SEGEN8.
LCD_SEG33	PB1				LCD segment line 33. Segments 32, 33, 34 and 35 are controlled by SEGEN8.
LCD_SEG34	PB2				LCD segment line 34. Segments 32, 33, 34 and 35 are controlled by SEGEN8.
LCD_SEG35	PA7				LCD segment line 35. Segments 32, 33, 34 and 35 are controlled by SEGEN8.
LCD_SEG36	PA8				LCD segment line 36. Segments 36, 37, 38 and 39 are controlled by SEGEN9.
LCD_SEG37	PA9				LCD segment line 37. Segments 36, 37, 38 and 39 are controlled by SEGEN9.
LCD_SEG38	PA10				LCD segment line 38. Segments 36, 37, 38 and 39 are controlled by SEGEN9.
LCD_SEG39	PA11				LCD segment line 39. Segments 36, 37, 38 and 39 are controlled by SEGEN9.
LETIM0_OUT0	PD6	PB11	PF0	PC4	Low Energy Timer LETIM0, output channel 0.
LETIM0_OUT1	PD7	PB12	PF1	PC5	Low Energy Timer LETIM0, output channel 1.
LEU0_RX	PD5	PB14	PE15		LEUART0 Receive input.
LEU0_TX	PD4	PB13	PE14		LEUART0 Transmit output. Also used as receive input in half duplex communication.
LEU1_RX	PC7	PA6			LEUART1 Receive input.
LEU1_TX	PC6	PA5			LEUART1 Transmit output. Also used as receive input in half duplex communication.
LFXTAL_N	PB8				Low Frequency Crystal (typically 32.768 kHz) negative pin. Also used as an optional external clock input pin.
LFXTAL_P	PB7				Low Frequency Crystal (typically 32.768 kHz) positive pin.
PCNT0_S0IN	PC13	PE0	PC0		Pulse Counter PCNT0 input number 0.
PCNT0_S1IN	PC14	PE1	PC1		Pulse Counter PCNT0 input number 1.
PCNT1_S0IN	PC4	PB3			Pulse Counter PCNT1 input number 0.
PCNT1_S1IN	PC5	PB4			Pulse Counter PCNT1 input number 1.
PCNT2_S0IN	PD0	PE8			Pulse Counter PCNT2 input number 0.
PCNT2_S1IN	PD1	PE9			Pulse Counter PCNT2 input number 1.
TIM0_CC0	PA0	PA0	PF6	PD1	Timer 0 Capture Compare input / output channel 0.
TIM0_CC1	PA1	PA1	PF7	PD2	Timer 0 Capture Compare input / output channel 1.
TIM0_CC2	PA2	PA2	PF8	PD3	Timer 0 Capture Compare input / output channel 2.
TIM0_CDTI0	PA3	PC13	PF3	PC13	Timer 0 Complimentary Deat Time Insertion channel 0.

9. TQFP48 Package Specifications

9.1 TQFP48 Package Dimensions

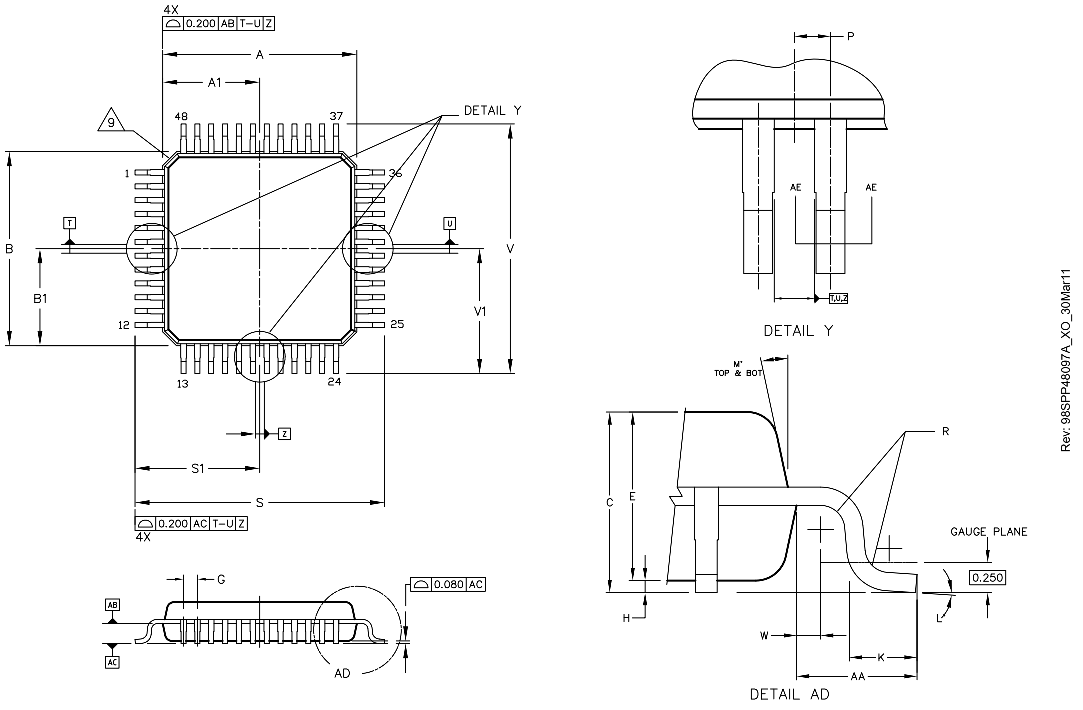

Figure 9.1. TQFP48

Note:

1. Dimensions and tolerance per ASME Y14.5M-1994
2. Control dimension: Millimeter
3. Datum plane AB is located at bottom of lead and is coincident with the lead where the lead existsfrom the plastic body at the bottom of the parting line.
4. Datums T, U and Z to be determined at datum plane AB.
5. Dimensions S and V to be determined at seating plane AC.
6. Dimensions A and B do not include mold protrusion. Allowable protrusion is 0.250 per side. Dimensions A and B do include mold mismatch and are determined at datum AB.
7. Dimension D does not include dambar protrusion. Dambar protrusion shall not cause the D dimensionto exceed 0.350.
8. Minimum solder plate thickness shall be 0.0076.
9. Exact shape of each corner is optional.

Table 9.1. QFP48 (Dimensions in mm)

DIM	MIN	NOM	MAX	DIM	MIN	NOM	MAX
A	—	7.000 BSC	—	M	—	12DEG REF	
A1	—	3.500 BSC	—	N	0.090	—	0.160
B	—	7.000 BSC	—	P	—	0.250 BSC	—
B1	—	3.500 BSC	—	R	0.150	—	0.250
C	1.000	—	1.200	S	—	9.000 BSC	—

9.2 TQFP48 PCB Layout

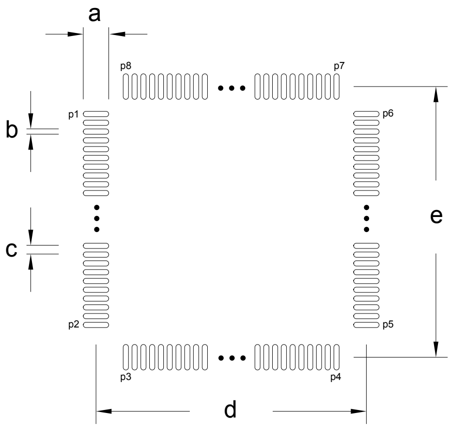

Figure 9.2. TQFP48 PCB Land Pattern

Table 9.2. TQFP48 PCB Land Pattern Dimensions (Dimensions in mm)

Symbol	Dim. (mm)	Symbol	Pin Number	Symbol	Pin Number
a	1.60	P1	1	P6	36
b	0.30	P2	12	P7	37
c	0.50	P3	13	P8	48
d	8.50	P4	24		
e	8.50	P5	25		

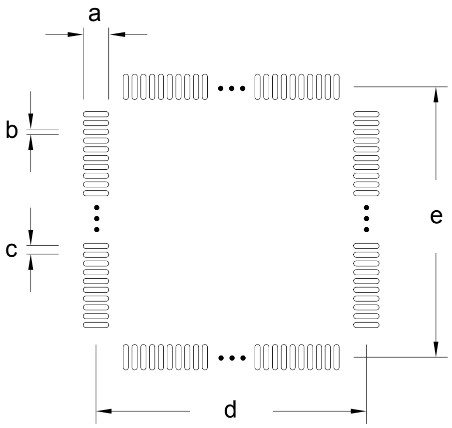

Figure 9.3. TQFP48 PCB Solder Mask

Table 9.3. TQFP48 PCB Solder Mask Dimensions (Dimensions in mm)

Symbol	Dim. (mm)
a	1.72
b	0.42
c	0.50
d	8.50
e	8.50

Symbol	Dim. (mm)
d	6.00
e	6.00
f	4.52
g	4.52

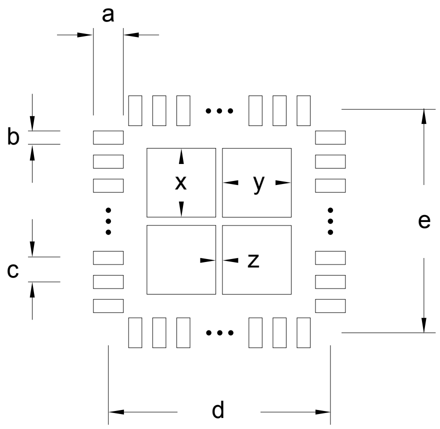

Figure 11.4. QFN32 PCB Stencil Design

Table 11.4. QFN32 PCB Stencil Design Dimensions (Dimensions in mm)

Symbol	Dim. (mm)
a	0.70
b	0.25
c	0.65
d	6.00
e	6.00
x	1.30
y	1.30
z	0.50

Note:

1. The drawings are not to scale.
2. All dimensions are in millimeters.
3. All drawings are subject to change without notice.
4. The PCB Land Pattern drawing is in compliance with IPC-7351B.
5. Stencil thickness 0.125 mm.
6. For detailed pin-positioning, see 5. Pin Definitions.

13.11 Revision 1.20

December 17th, 2010

This revision applies the following devices:

- EFM32G200
- EFM32G210
- EFM32G230
- EFM32G280
- EFM32G290
- EFM32G840
- EFM32G880
- EFM32G890

Increased max storage temperature.

Added data for <150°C and <70°C on Flash data retention.

Changed latch-up sensitivity test description.

Added IO leakage current.

For LQFP100 devices, updated ESD CDM value.

Added Flash current consumption.

Updated HFRCO data.

Updated LFRCO data.

Added graph for ADC Absolute Offset over temperature.

Added graph for ADC Temperature sensor readout.

13.12 Revision 1.11

November 17th, 2010

This revision applies the following devices:

- EFM32G200
- EFM32G210
- EFM32G230
- EFM32G280
- EFM32G290
- EFM32G840
- EFM32G880
- EFM32G890

Corrected maximum DAC clock speed for continuous mode.

Added DAC sample-hold mode voltage drift rate.

Added pulse widths detected by the HFXO glitch detector.

Added power sequencing information to Power Management section.